

[54] CONNECTOR HOUSING WITH
DETACHABLE SEMICONDUCTOR
COMPONENTS

[75] Inventors: Sizuo Tsubokura; Itsuo Takayanagi,
both of Shizuoka, Japan

[73] Assignee: Yazaki Corporation, Tokyo, Japan

[**] Term: 14 Years

[21] Appl. No.: 140,837

[22] Filed: Jan. 4, 1988

[52] U.S. Cl. D13/146

[58] Field of Search D13/133, 146; 439/344,
439/353, 357, 660, 682, 685, 686, 687, 695, 696,
712, 713, 350, 701

[56] References Cited

U.S. PATENT DOCUMENTS

D. 218,747 9/1970 Bennett D13/24
4,273,403 6/1981 Cairns 439/357 X
4,709,976 12/1987 Nakama et al. 439/350

FOREIGN PATENT DOCUMENTS

2618952 2/1989 France 439/701

Primary Examiner—Susan J. Lucas

Assistant Examiner—Joel Sincavage
Attorney, Agent, or Firm—Sughrue, Mion, Zinn,
Macpeak & Seas

[57] CLAIM

The ornamental design for a connector housing with detachable semiconductor components, as shown and described.

DESCRIPTION

FIG. 1 is a front, top and right side perspective view of a connector housing with detachable semiconductor components showing our new design;
FIG. 2 is a front elevational view thereof;
FIG. 3 is a right side elevational view thereof, the opposite side being a mirror image thereof;
FIG. 4 is a top plan view thereof;
FIG. 5 is a rear elevational view thereof;
FIG. 6 is a front elevational view thereof with the three detachable semiconductor components removed for the purpose of a complete disclosure; and
FIG. 7 is a perspective view thereof with the uppermost semiconductor component withdrawn from the connector housing for the purposes of a complete disclosure. Conductors shown in broken lines leading to the connector housing are environmental elements for illustrative purposes only and form no part of the claimed design.

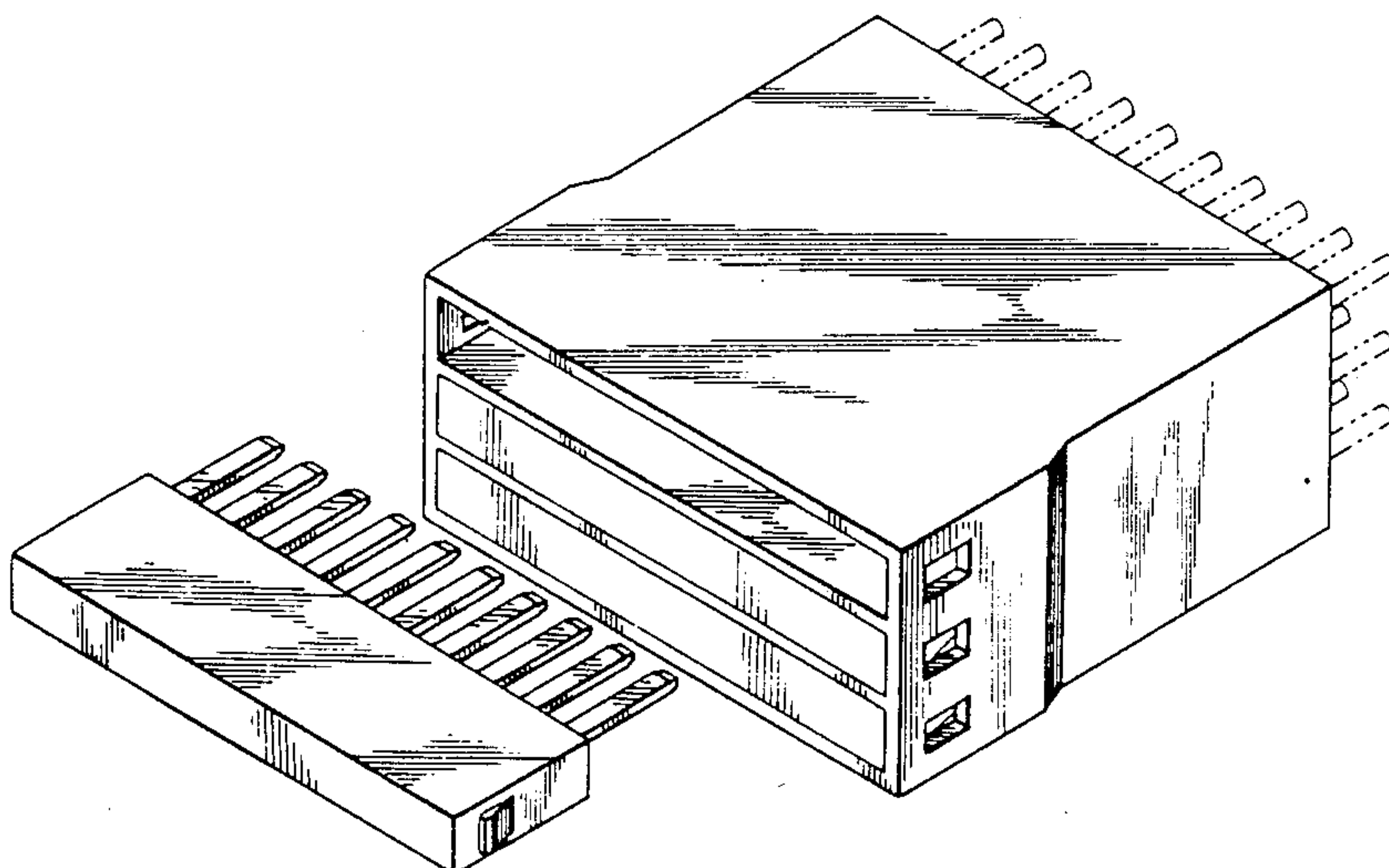


FIG. 1

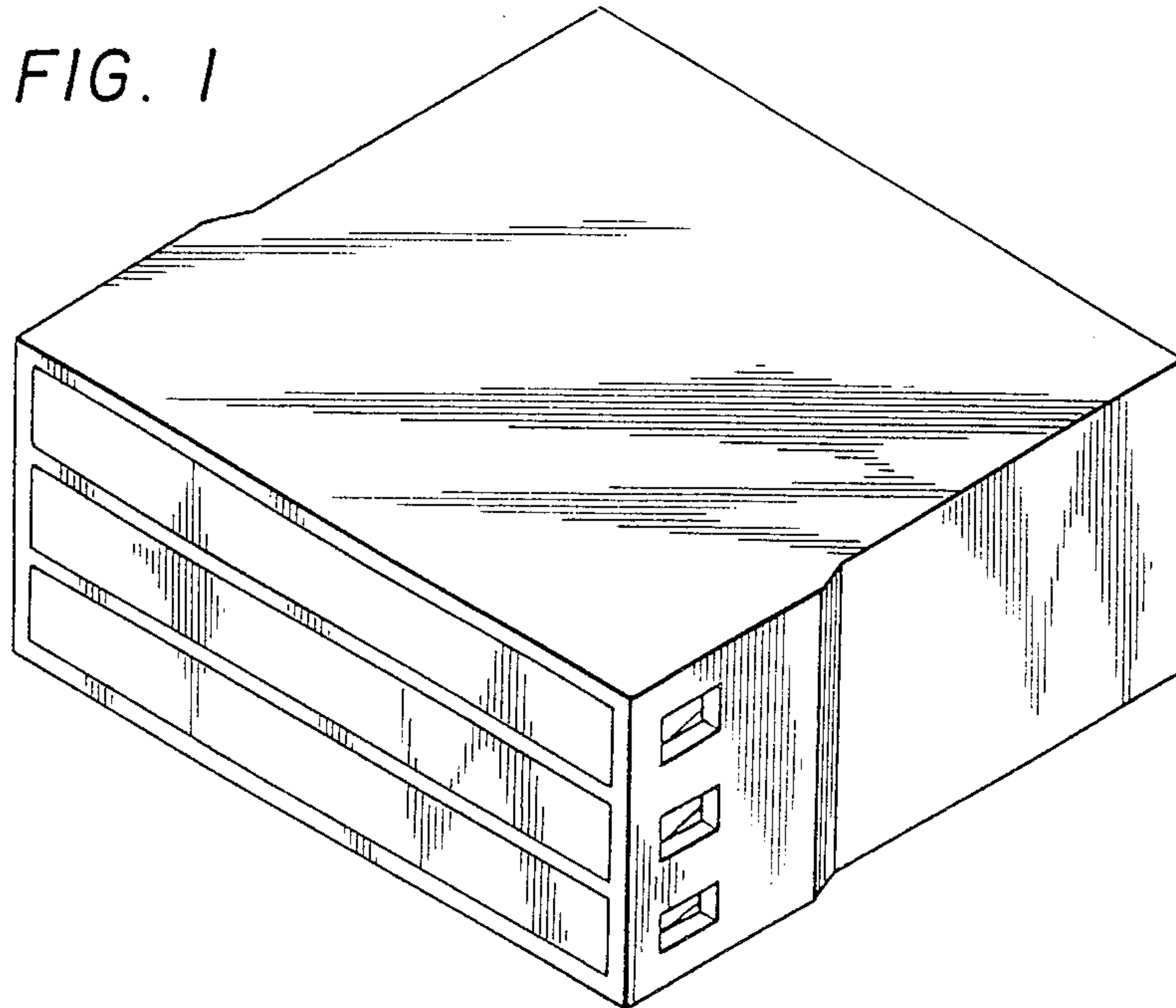


FIG. 2

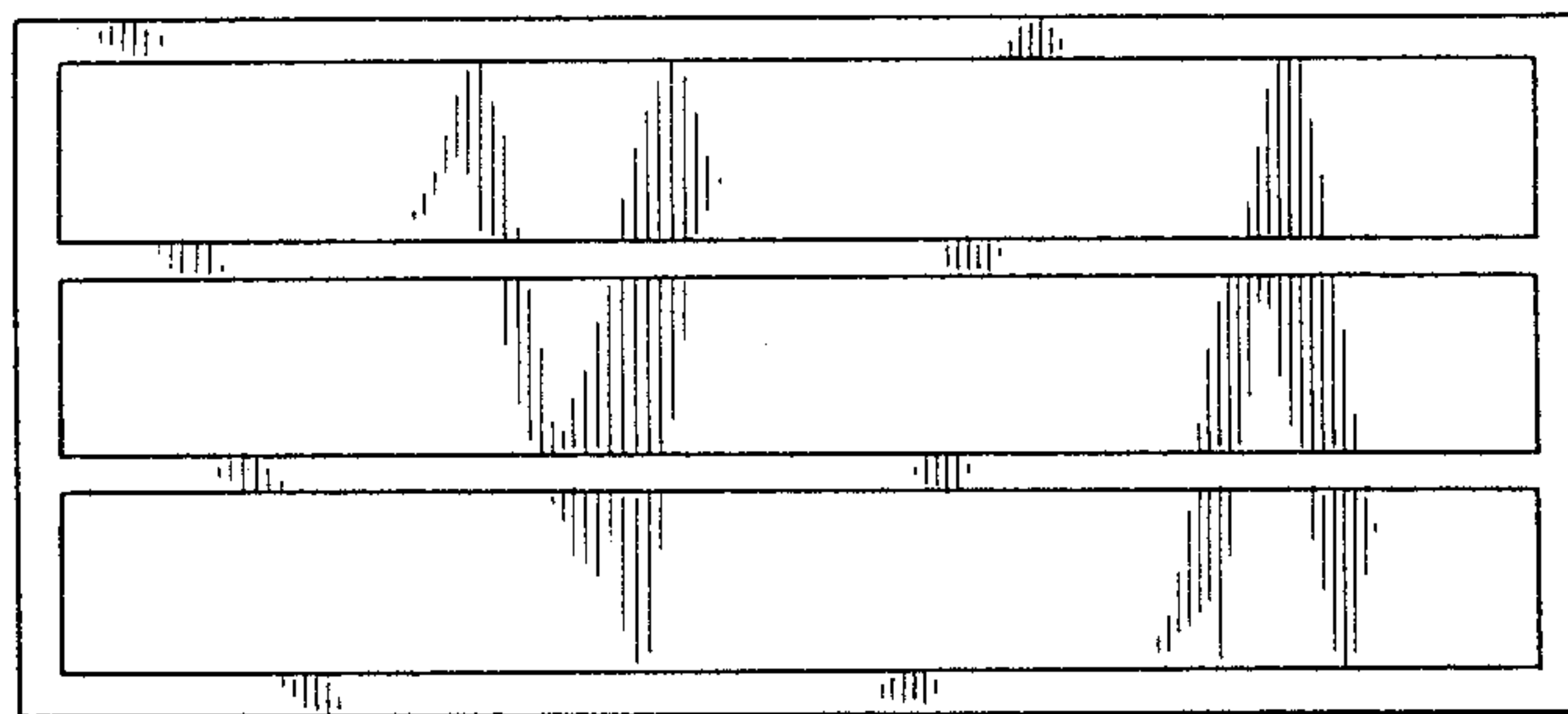


FIG. 3

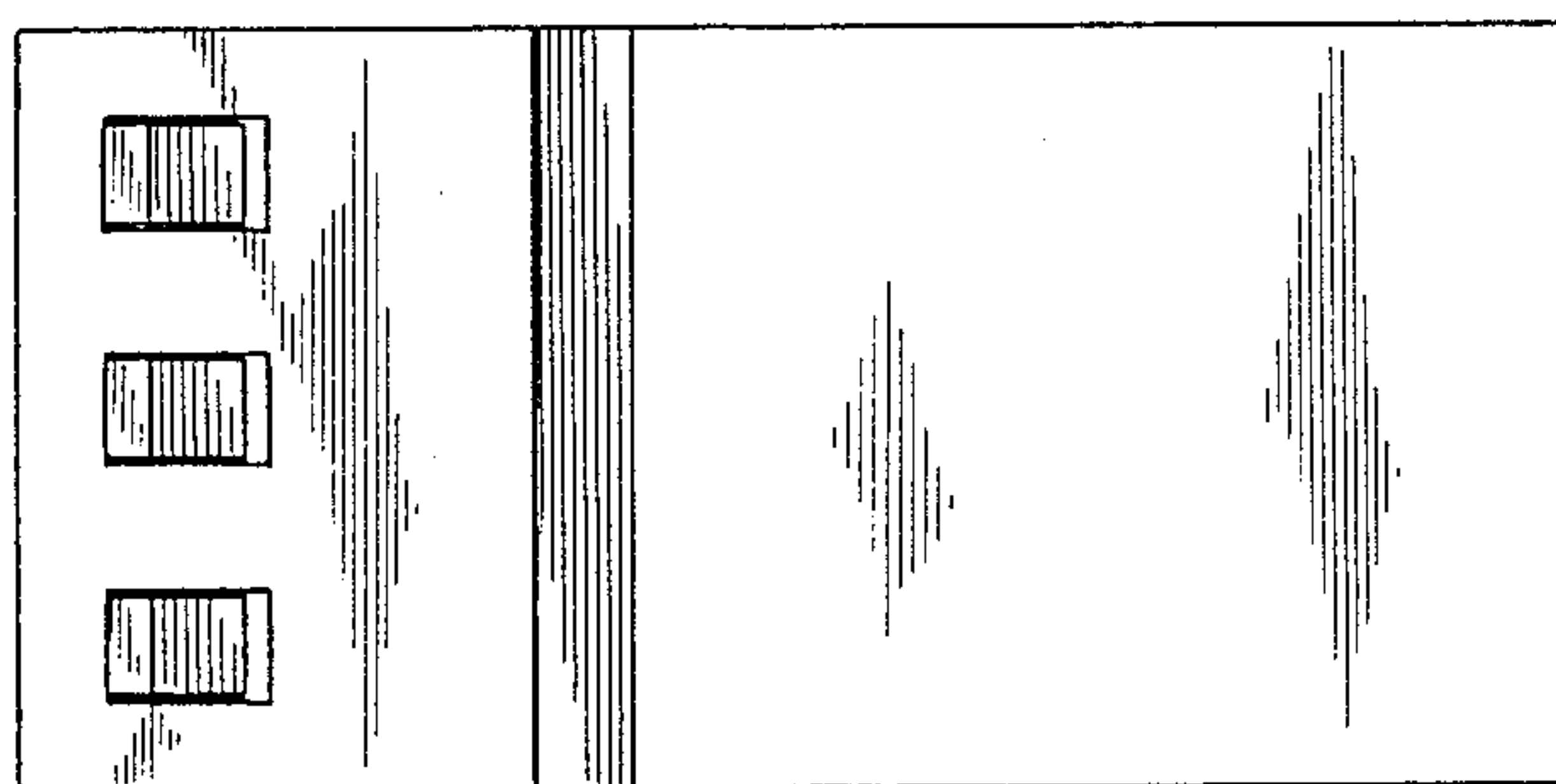


FIG. 4

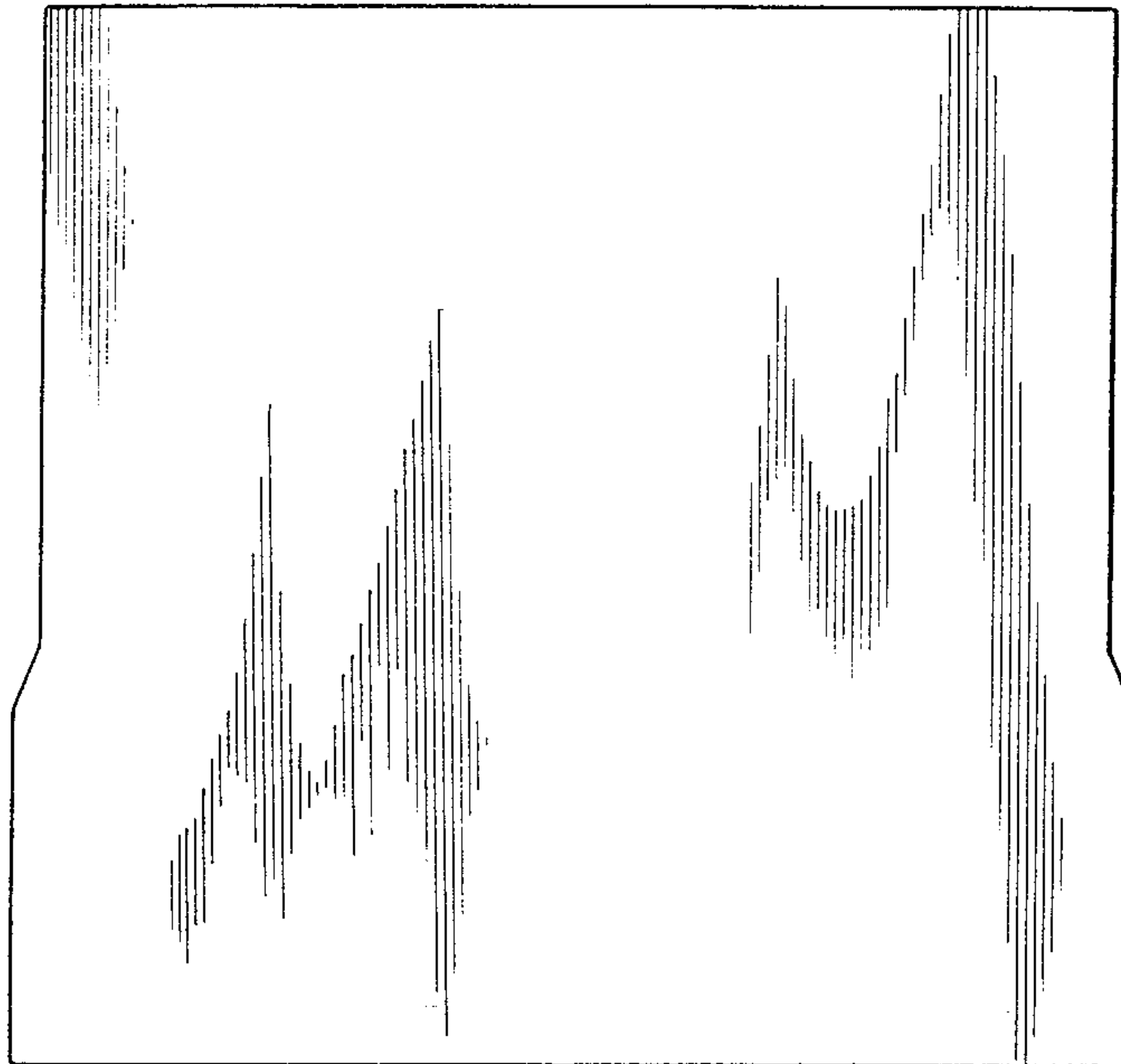


FIG. 5

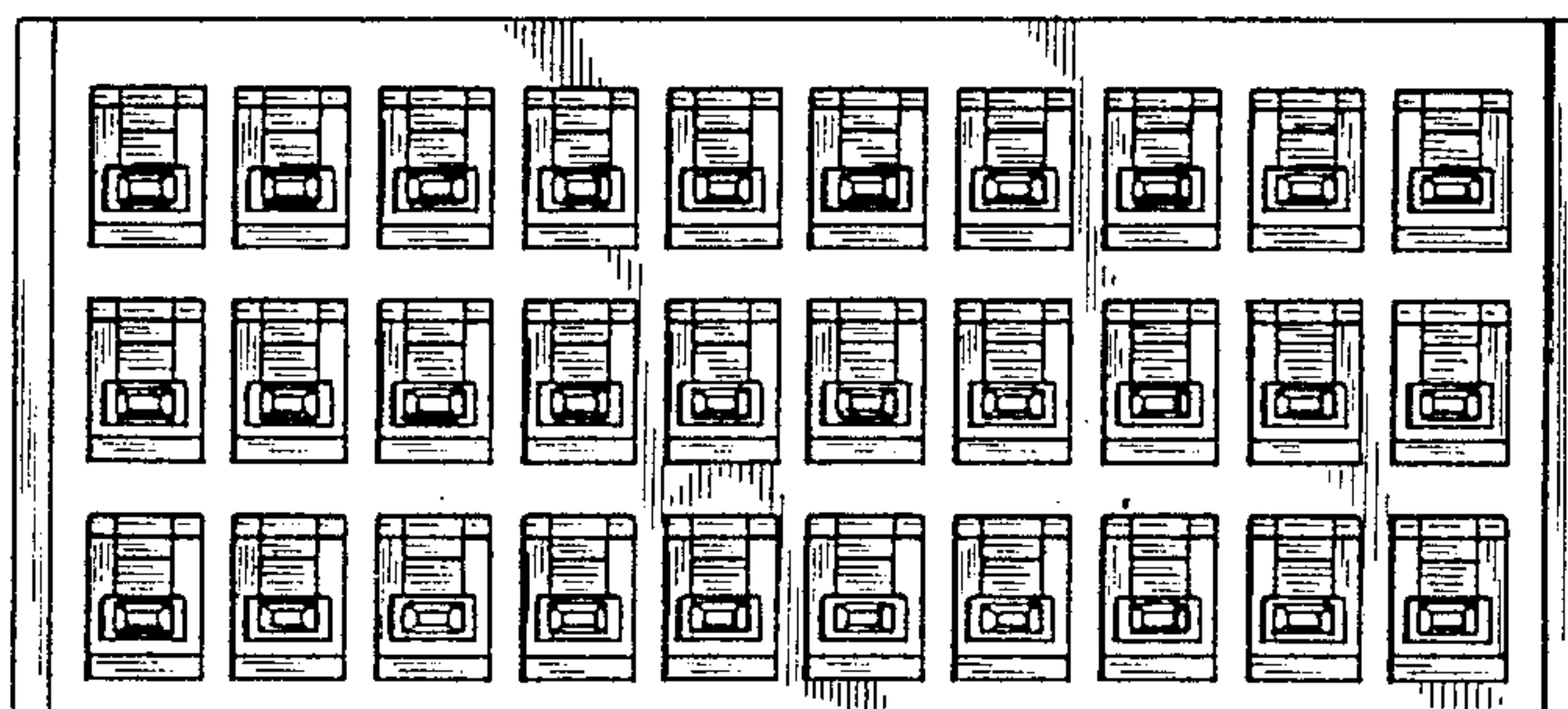


FIG. 6

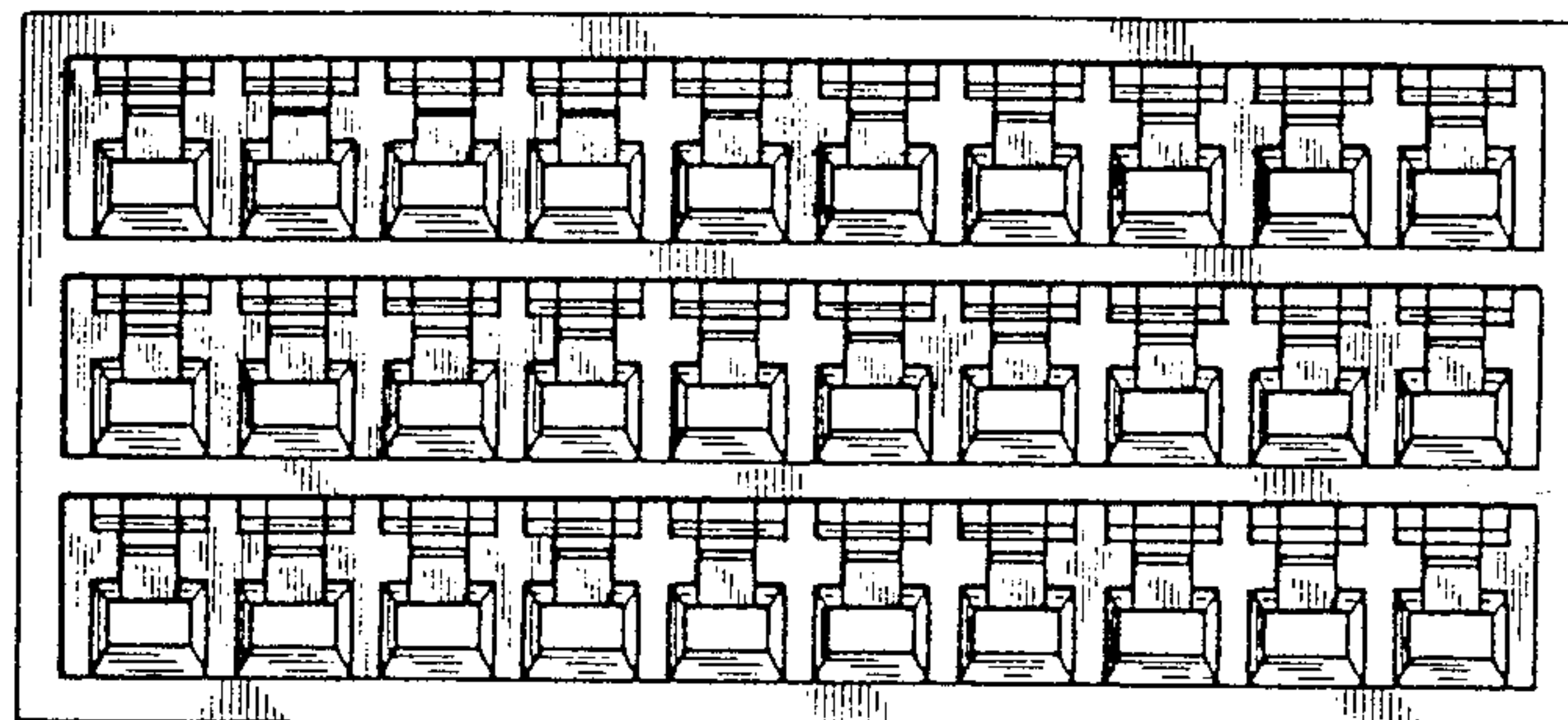


FIG. 7

